

Vishay Semiconductors

# Ultrafast Rectifier, 10 A FRED Pt®



TO-220AB

Base common cathode 2								
Anode 0	O 2 Commo cathod							

PRODUCT SUMMARY						
Package	TO-220AB					
I <sub>F(AV)</sub>	2 x 5 A					
$V_{R}$	200 V					
V <sub>F</sub> at I <sub>F</sub>	0.87 V					
t <sub>rr</sub> typ.	See Recovery table					
T <sub>J</sub> max.	175 °C					
Diode variation	Common cathode					

#### **FEATURES**

- Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS
COMPLIANT
HALOGEN
FREE

#### **DESCRIPTION / APPLICATIONS**

VS-MUR.. series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS								
PARAMETER		SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Peak repetitive reverse voltage		$V_{RRM}$		200	V			
Average rectified forward average	per leg	I		5				
Average rectified forward current	total device	I <sub>F(AV)</sub>	Rated V <sub>R</sub> , T <sub>C</sub> = 149 °C	10				
Non-repetitive peak surge current per leg		I <sub>FSM</sub>		50	Α			
Peak repetitive forward current per leg		I <sub>FM</sub>	Rated $V_R$ , square wave, 20 kHz $T_C = 149  ^{\circ}C$	10				
Operating junction and storage temp	eratures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C			

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	TEST CONDITIONS MIN. TYP. MAX.					
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	Ι <sub>R</sub> = 100 μΑ	200	-	-			
		I <sub>F</sub> = 5 A, T <sub>J</sub> = 125 °C	-	0.87	0.99	V		
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 10 A, T <sub>J</sub> = 125 °C	-	1.02	1.20	ļ		
		I <sub>F</sub> = 10 A	-	1.12	1.25			
Payaraa laakaga aurrant		V <sub>R</sub> = V <sub>R</sub> rated	-	-	10			
Reverse leakage current I <sub>R</sub>		T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	-	250	μΑ		
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V	-	8	-	pF		
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	=	8.0	-	nH		



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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time		$I_F = 1.0 \text{ A}, dI_F/dt =$	$50 \text{ A/}\mu\text{s}, \text{ V}_{\text{R}} = 30 \text{ V}$	-	-	35			
		I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>REC</sub> = 0.25 A		-	-	25	no		
	t <sub>rr</sub>	T <sub>J</sub> = 25 °C	$I_F = 5 A$ $dI_F/dt = 200 A/\mu s$ $V_R = 160 V$	-	24	-	ns		
		T <sub>J</sub> = 125 °C			-	35	-		
Dook roopyon, ourront	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	3.3	-	۸		
Peak recovery current		T <sub>J</sub> = 125 °C		-	5.0	-	A		
Reverse recovery charge	0	T <sub>J</sub> = 25 °C	-n3 •	-	33	-	nC		
	Q <sub>rr</sub>	T <sub>J</sub> = 125 °C		-	76	-	110		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C		
Thermal resistance, junction to case per leg	R <sub>thJC</sub>		-	-	5			
Thermal resistance, junction to ambient per leg	R <sub>thJA</sub>		-	-	50	°C/W		
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.5	-			
Weight			-	2.0	-	g		
vveigni			-	0.07	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-220AB		MUR1	020CT			

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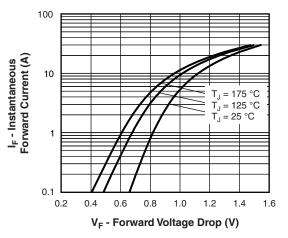


Fig. 1 - Typical Forward Voltage Drop Characteristics

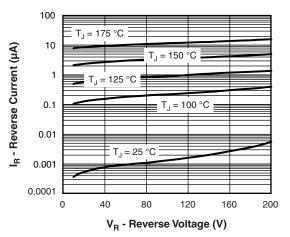


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

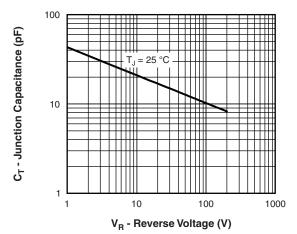


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

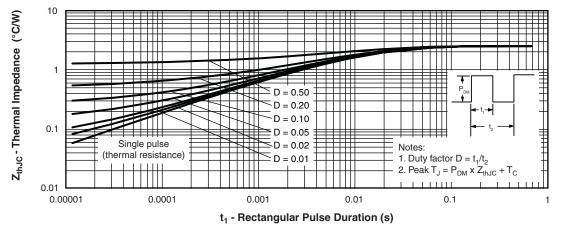


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

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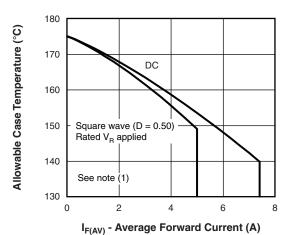


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

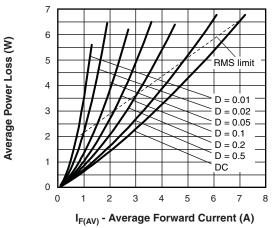


Fig. 6 - Forward Power Loss Characteristics

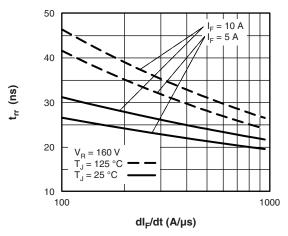


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

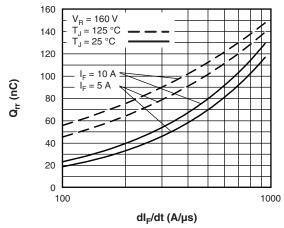


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $\begin{array}{l} \text{(1)} \ \ \text{Formula used:} \ T_C = T_J - (Pd + Pd_{REV}) \times R_{th,JC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \ \text{at } (I_{F(AV)}/D) \ \text{(see fig. 6)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \ \text{(1 - D)}; \ I_R \ \text{at } V_{R1} = \text{Rated } V_R \\ \end{array}$ 

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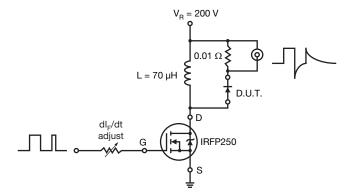
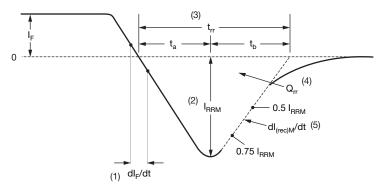


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dI<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  ${\rm Q_{rr}}$  area under curve defined by  ${\rm t_{rr}}$  and  ${\rm I_{RRM}}$

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

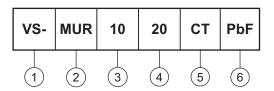
(5) dl<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 10 - Reverse Recovery Waveform and Definitions

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#### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

Ultrafast MUR series

Current rating (10 = 10 A)

Voltage rating (20 = 200 V)

- CT = center tap (dual) TO-220/D<sup>2</sup>PAK/TO-262

6 - Environmental digit:

PbF = lead (Pb)-free and RoHS-compliant

-N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)								
PREFERRED P/N QUANTITY PER T/R MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION								
VS-MUR1020CTPbF	50	1000	Antistatic plastic tube					
VS-MUR1020CT-N3	50	1000	Antistatic plastic tube					

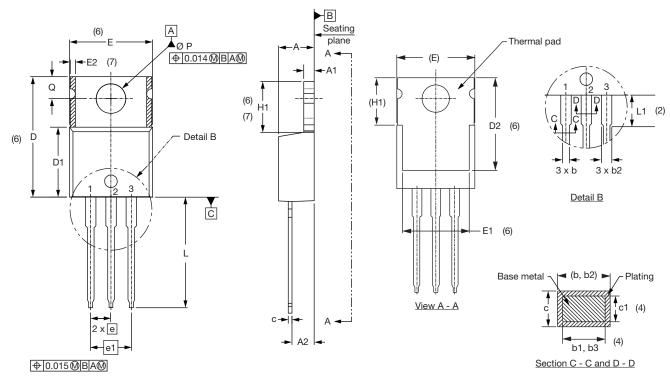
LINKS TO RELATED DOCUMENTS						
Dimensions <u>www.vishay.com/doc?95222</u>						
Part marking information	TO-220ABPbF	www.vishay.com/doc?95225				
Fait marking information	TO-220AB-N3	www.vishay.com/doc?95028				



## Vishay Semiconductors

## **TO-220AB**

#### **DIMENSIONS** in millimeters and inches



# Lead tip

#### Lead assignments

#### <u>Diodes</u>

- 1. Anode/open
- 2. Cathode
- 3. Anode

#### Conforms to JEDEC outline TO-220AB

SYMBOL	MILLIMETERS		INCHES		NOTES	
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.25	4.65	0.167	0.183		
A1	1.14	1.40	0.045	0.055		
A2	2.56	2.92	0.101	0.115		
b	0.69	1.01	0.027	0.040		
b1	0.38	0.97	0.015	0.038	4	
b2	1.20	1.73	0.047	0.068		
b3	1.14	1.73	0.045	0.068	4	
С	0.36	0.61	0.014	0.024		
c1	0.36	0.56	0.014	0.022	4	
D	14.85	15.25	0.585	0.600	3	
D1	8.38	9.02	0.330	0.355		
D2	11.68	12.88	0.460	0.507	6	

SYMBOL	MILLIM	IETERS	INCHES		NOTES
STIMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Е	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
е	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØΡ	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	
θ	90° t	0° to 93° 90° to 93		o 93°	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline



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